



Identification and Validation of Analytical Chemistry Methods for Detecting Composite Surface Contamination and Moisture

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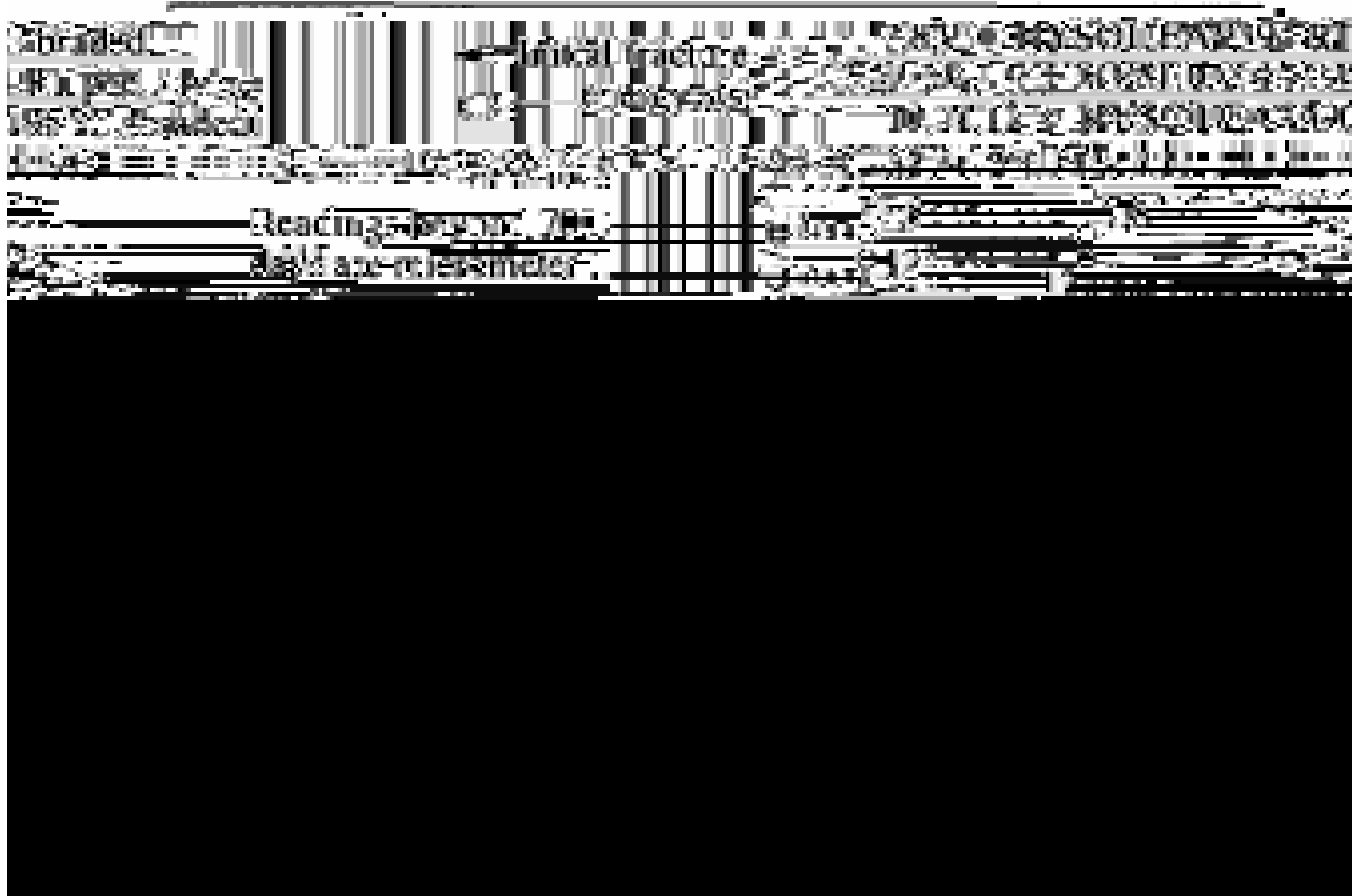
Weihoa Zhang, Dwayne McDaniel, Rajiv Srivastava and
Richard Burton
Florida International University



- **Motivation and Key Issues**
 - Adhesive bonding has been used in the manufacture and repair as a direct competition to mechanical fastening.
 - Adherent surface preparation is a critical issue to the structural integrity and durability of bonded structures.
- **Objective**
 - benchmark surface preparation quality assurance methods
 - identify and validate definitive analytical chemistry methods to provide sufficient in-field quality assurance.
- **Approach**
 - Literature review and analysis
 - Surface chemistry analysis
 - Electrochemical sensor development
 - Experimental validation

- Literature database, complete
- Summary of literature review
 - Surface treatment, complete
 - Surface chemistry analyses, complete
- An electrochemical sensor for surface chemistry analysis, testing in progress
- Carbon nano-tube sensor for humidity sensing, testing in progress
- AFM/SEM study of surface-contamination (peel-plies, etc), testing in progress

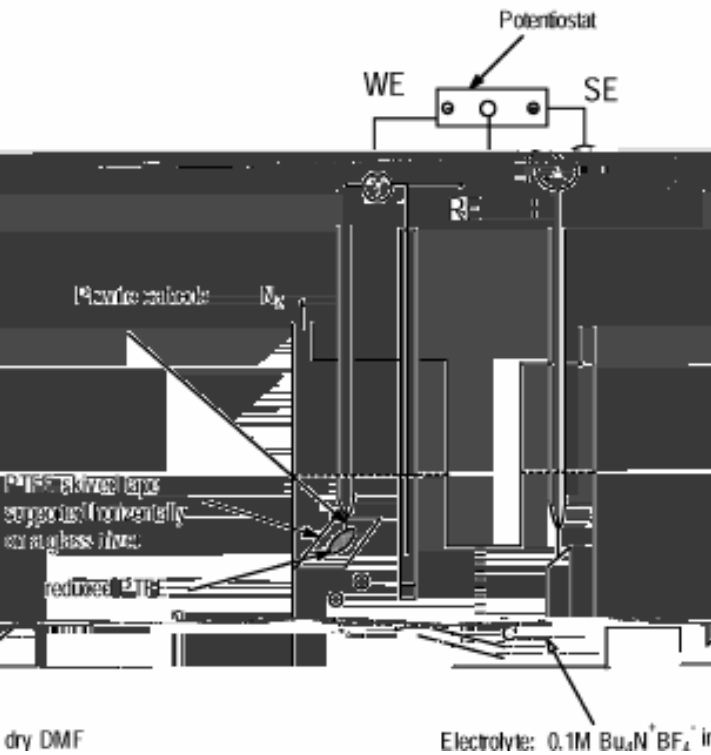
Literature Review: Effect of Various Surface Pretreatment Method



Literature Review: Concentration of Oxygen versus Strength

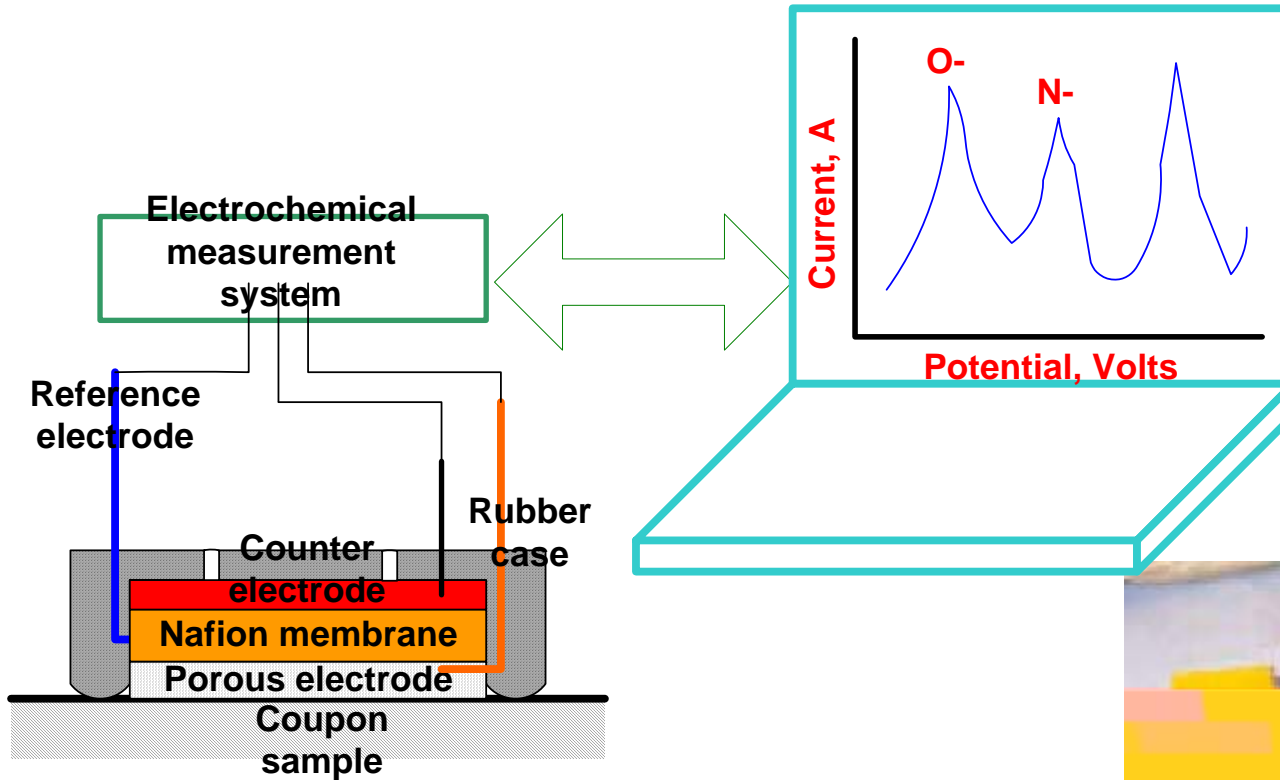
Polymer	Treatment	Surface composition (at%)	Failure load/N
O			C
HDPE			
0.0	400	No treatment	100.0
4.5	1330	2.1 V, Pt edge, 50 passes	95.5
3.8	1320	2.4 V, Pt edge, 50 passes	96.2
7.6	1110	2.9 V, Pt disc, 5 min	92.4
PP			
0.0	0	No treatment	100.0
—	267	3.25 M nitric acid, 60 s	—
—	267	11 M H ₂ SO ₄ , 50 passes	—
—	93.1	6.9	2560
—	100	0	50
—	—	—	270
—	—	—	—
SBS	No-treatment	100.0	0.0
—	2.6 V, Pt edge, 50 passes	93.6	—
—	100.0	0.0	550
—	94.5	5.5	670
PS	No-treatment	—	—
—	2.9 V, Pt disc, 300 s	—	—





D.M. Brewis, R.H. Dahm | International Journal of Adhesion & Adhesives 21 (2001) 397-409

Solid-State Electrochemical Sensor



- Ag(II)/Ag(I) $E^0=1.98 \text{ V}$
- Ag^+/Ag $E^0=0.8 \text{ V}$

- Ce(IV)/Ce(III) $E^0=1.72 \text{ V}$

Solid-State Electrolyte



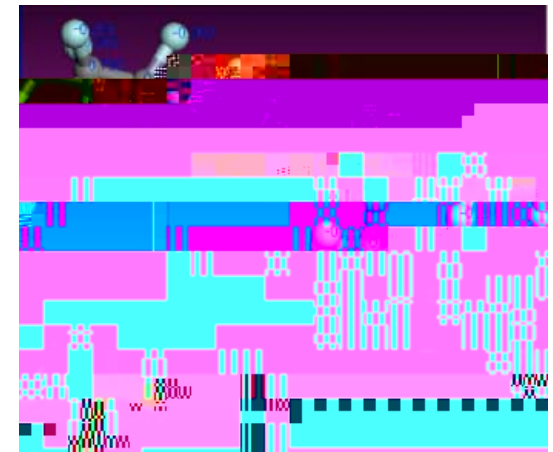
Nafion + Nafion Resin
(Sulfonated tetrafluorethylene copolymer)

Extremely resistant to chemical attack

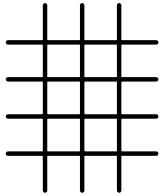
Proton conductor

Strong proton donor and free electron acceptor-superacid catalysts (neutral pH)

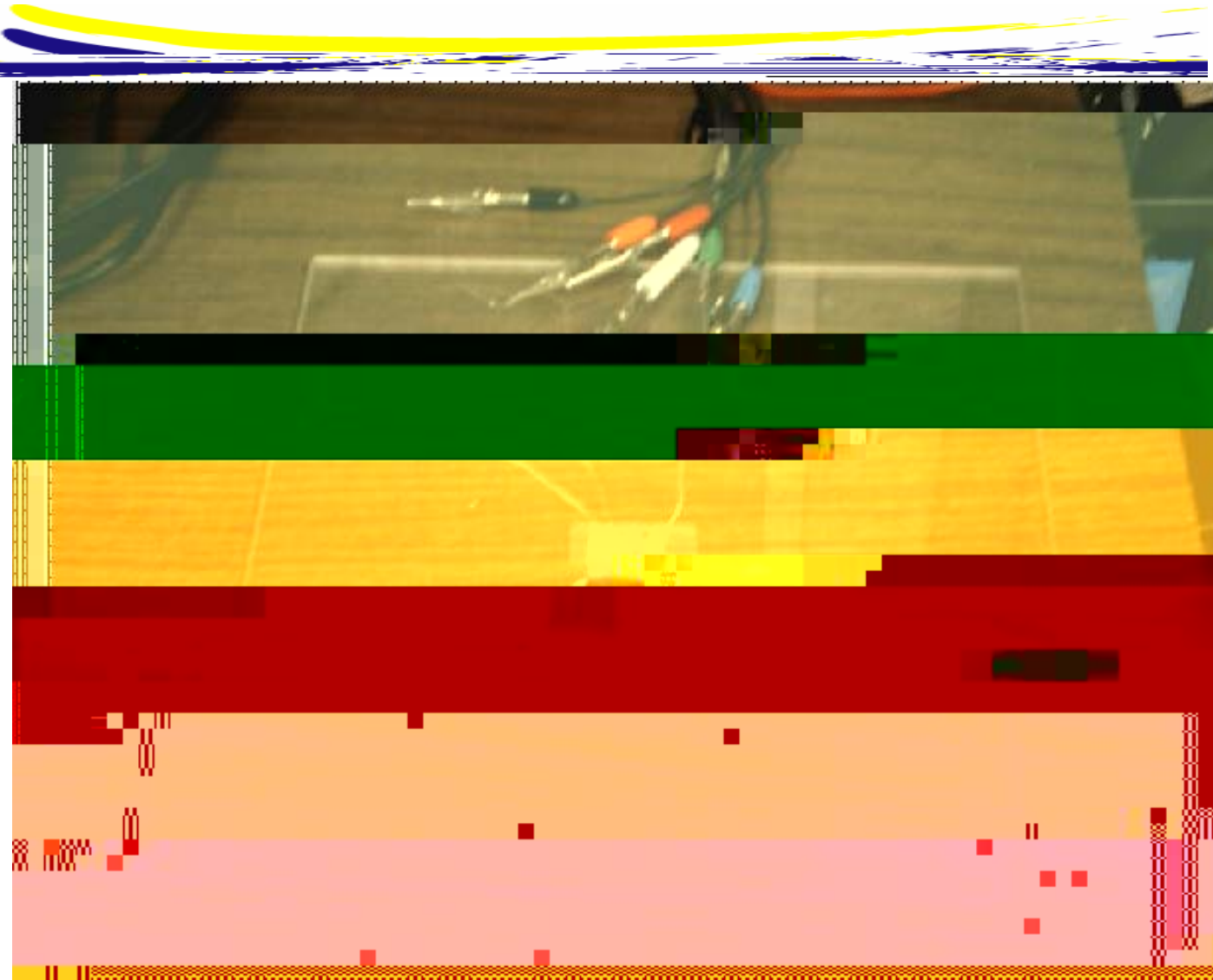
Minimum oxidation and reduction of water



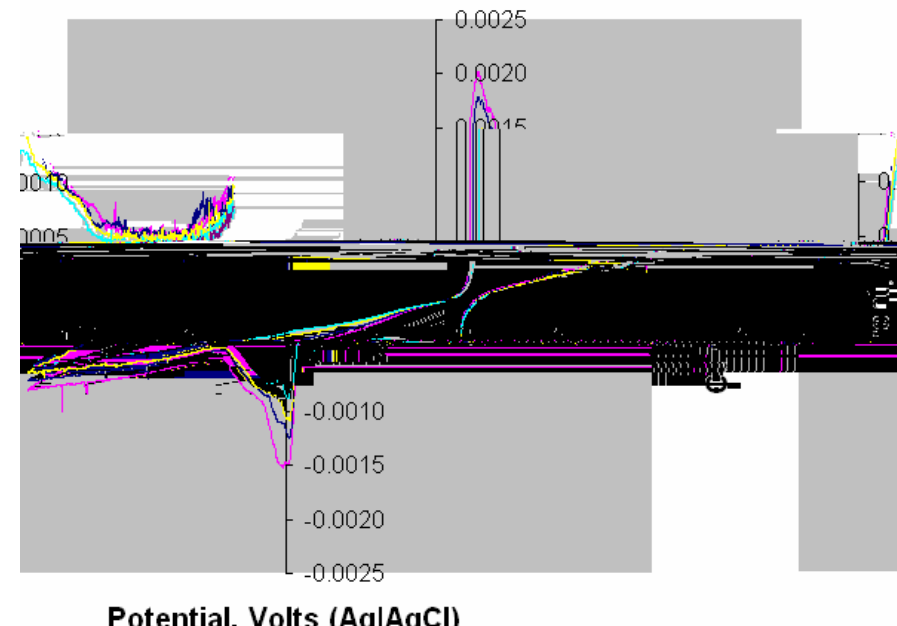
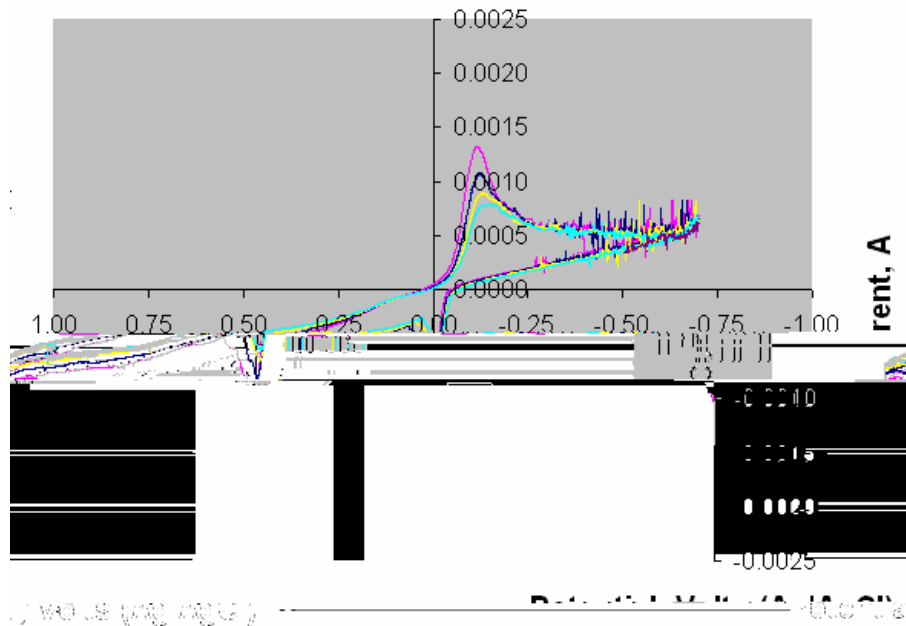
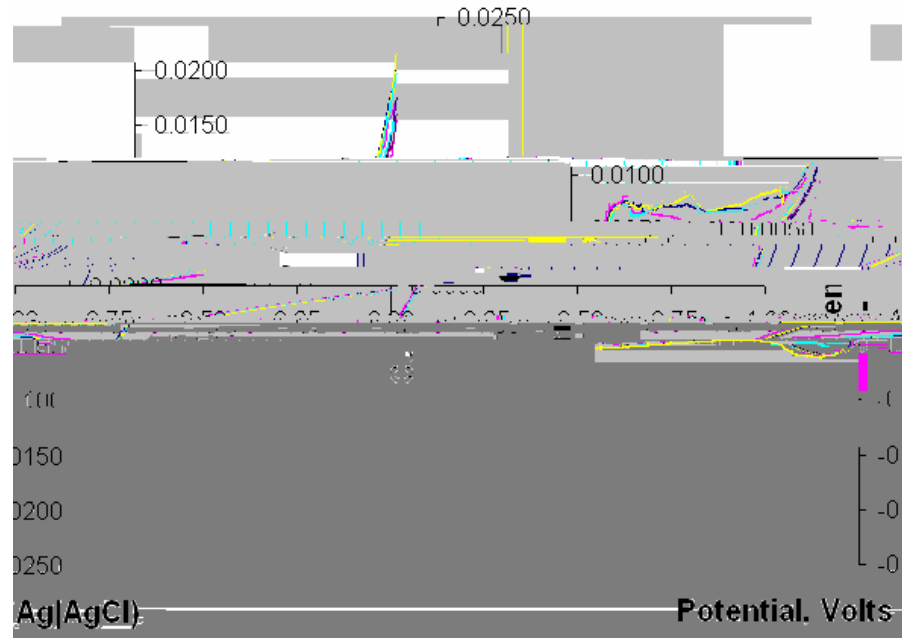
JAMS



Solid-state Electrochemical Sensor



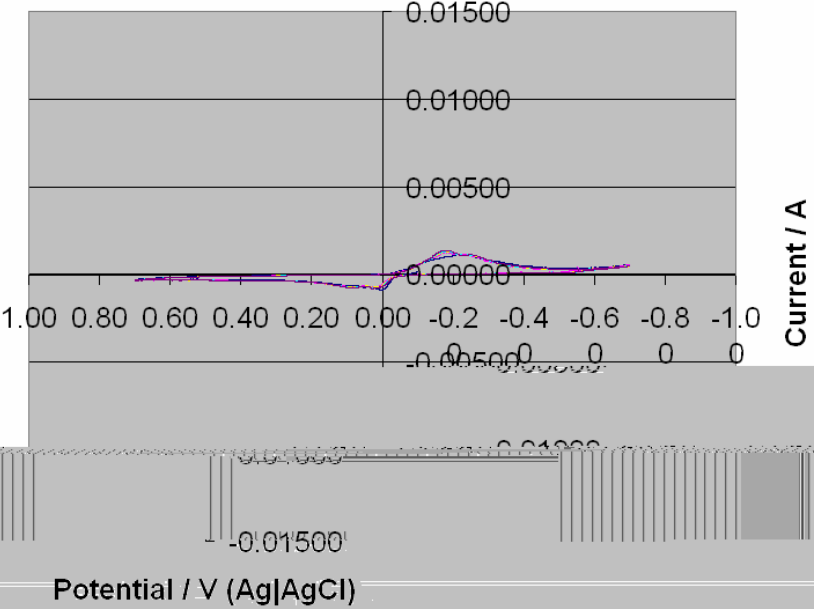
Treated with sulfuric acid



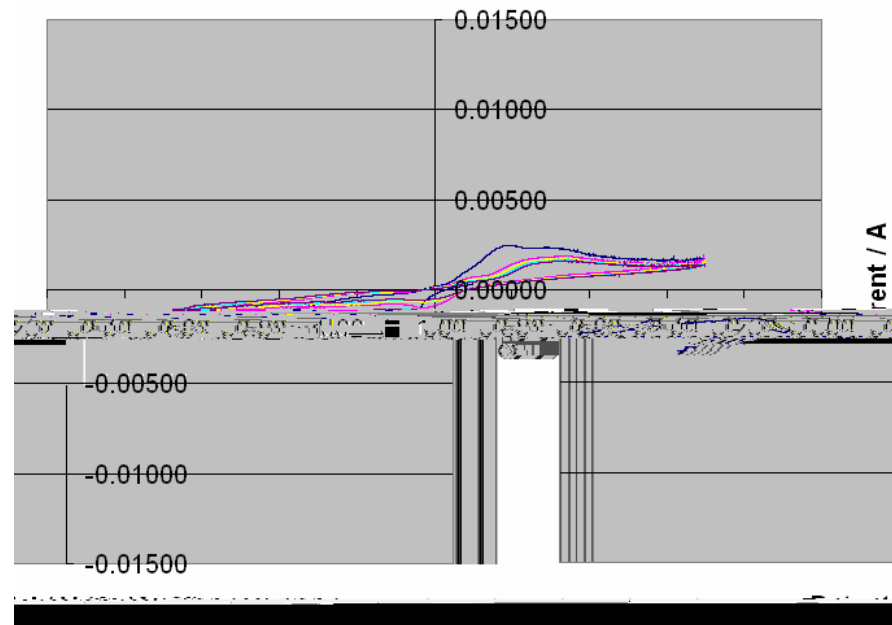
Original acrylic plastic surface

Polished acrylic plastic surface

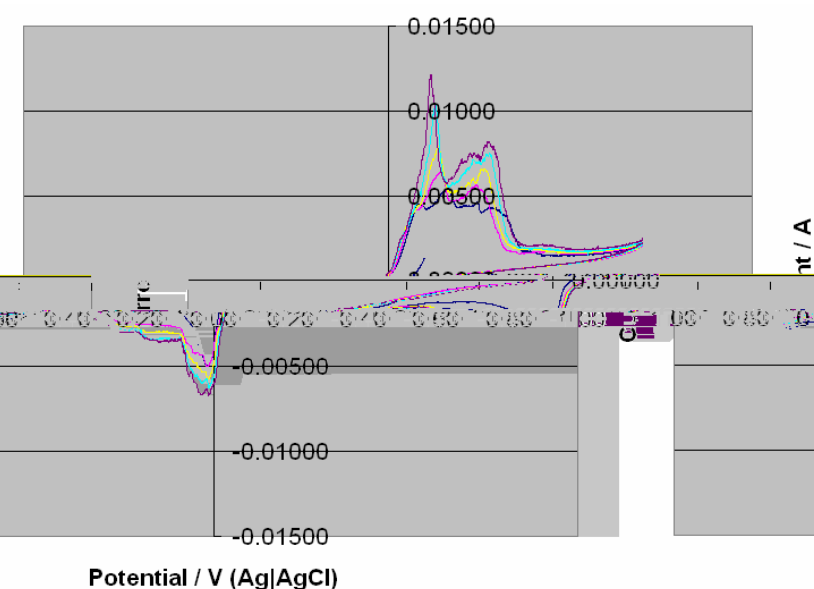
Original acrylic plastic surface



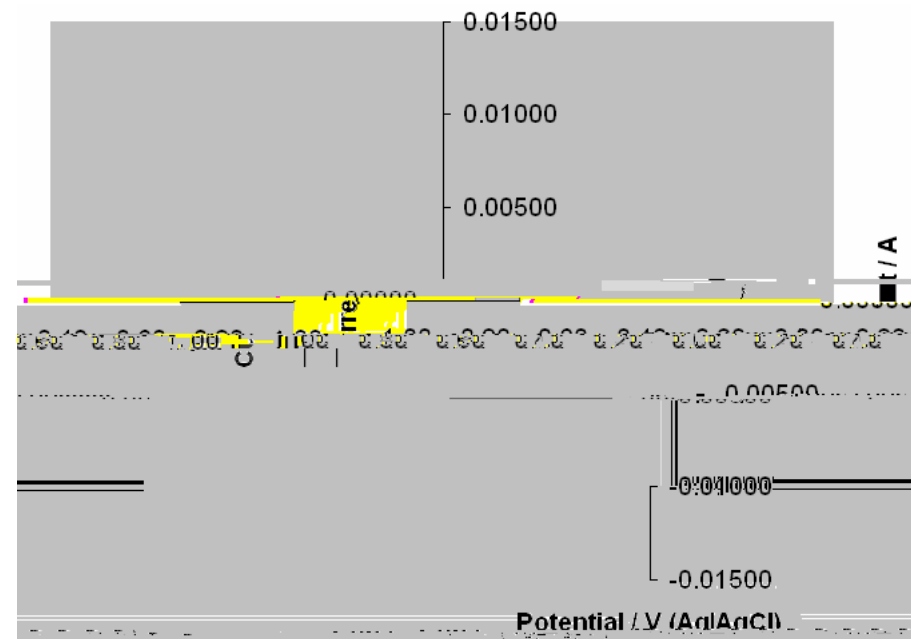
Original peel ply sample



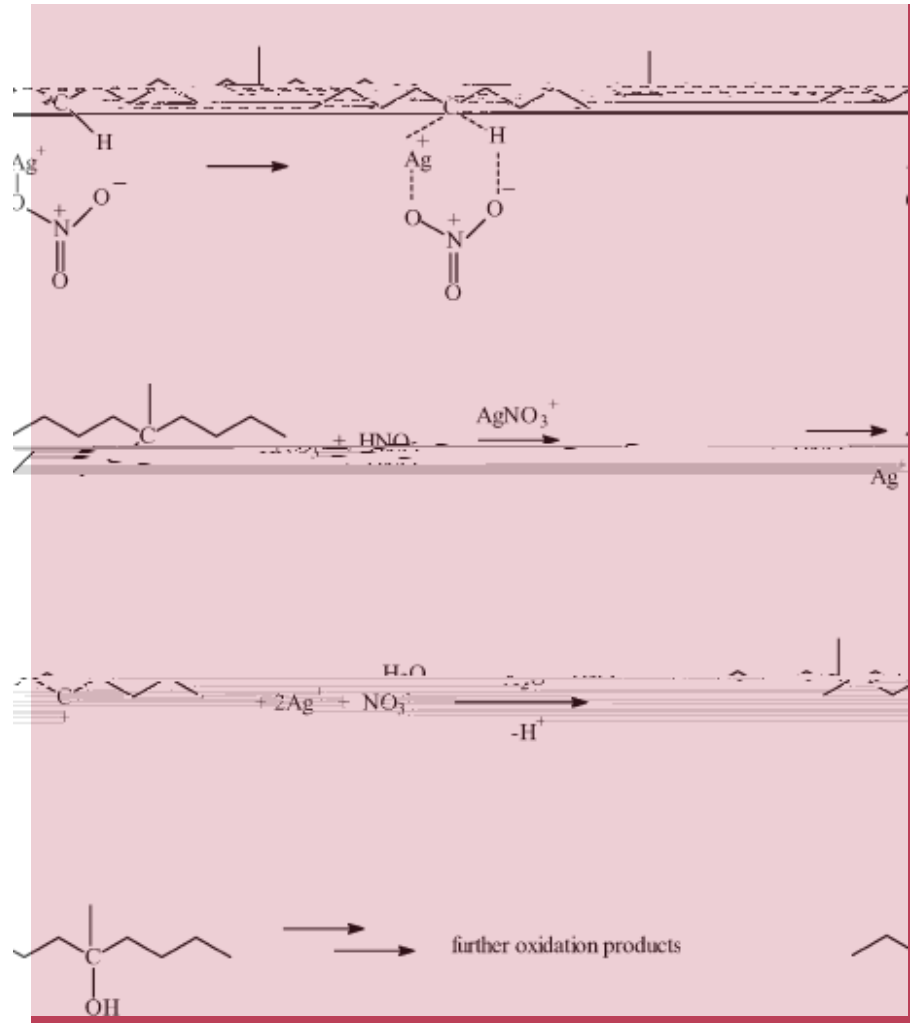
Polished sample



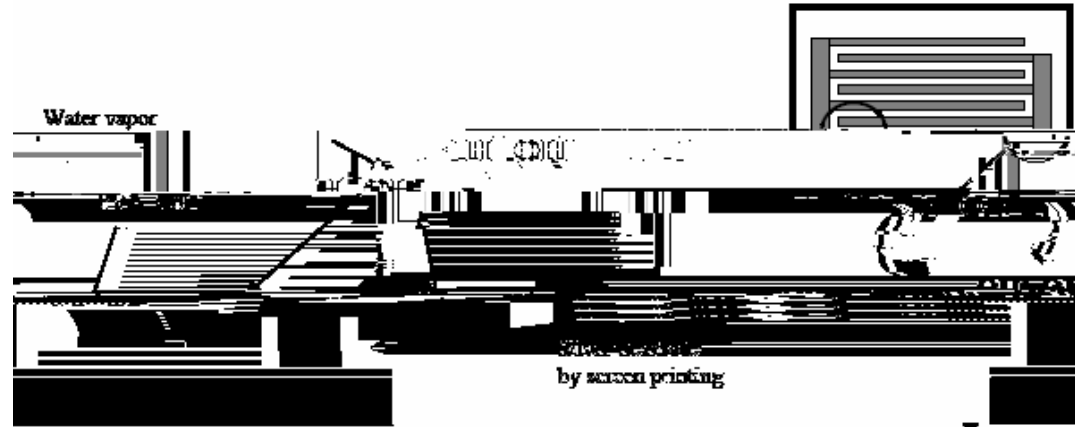
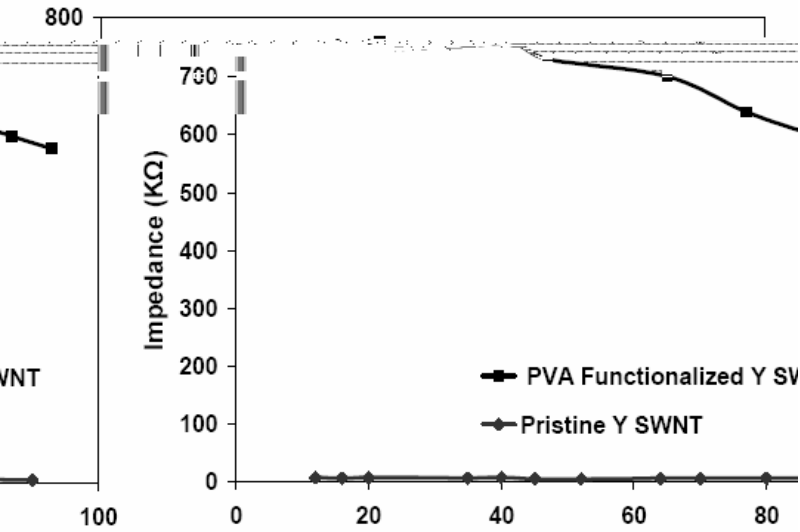
Sulfuric acid treated sample



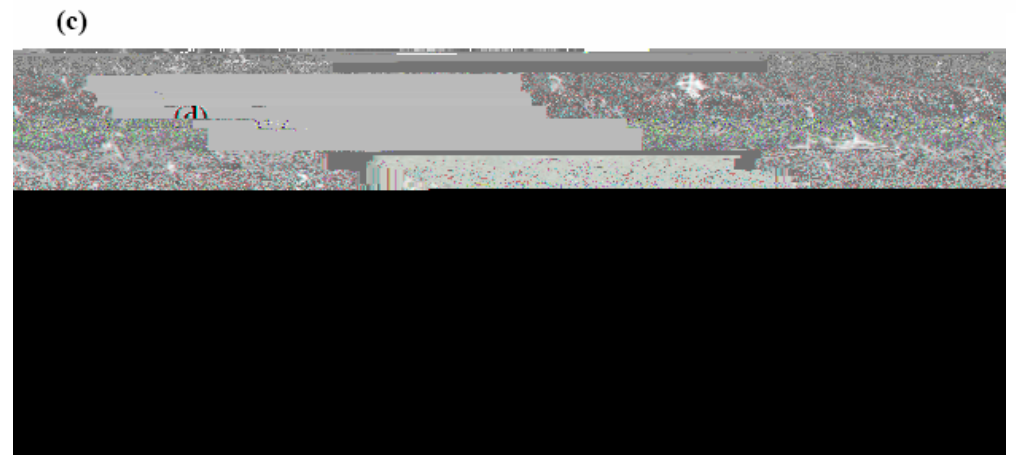
In air



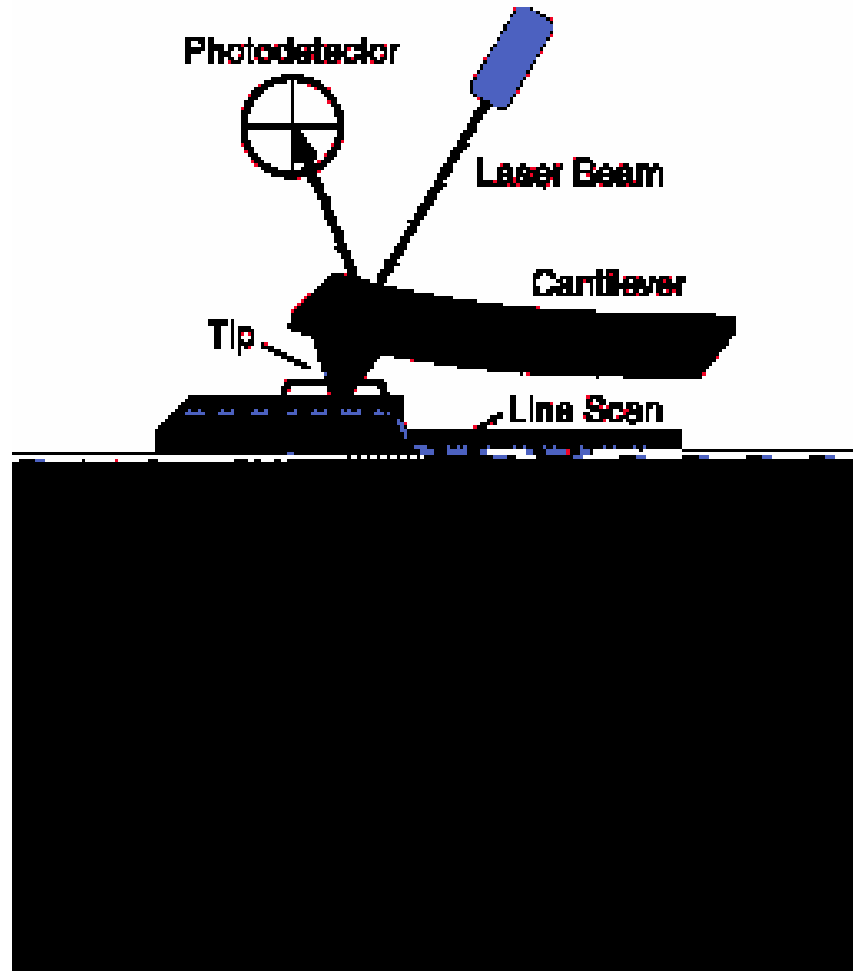
Carbon Nanotube Based Humidity Sensor



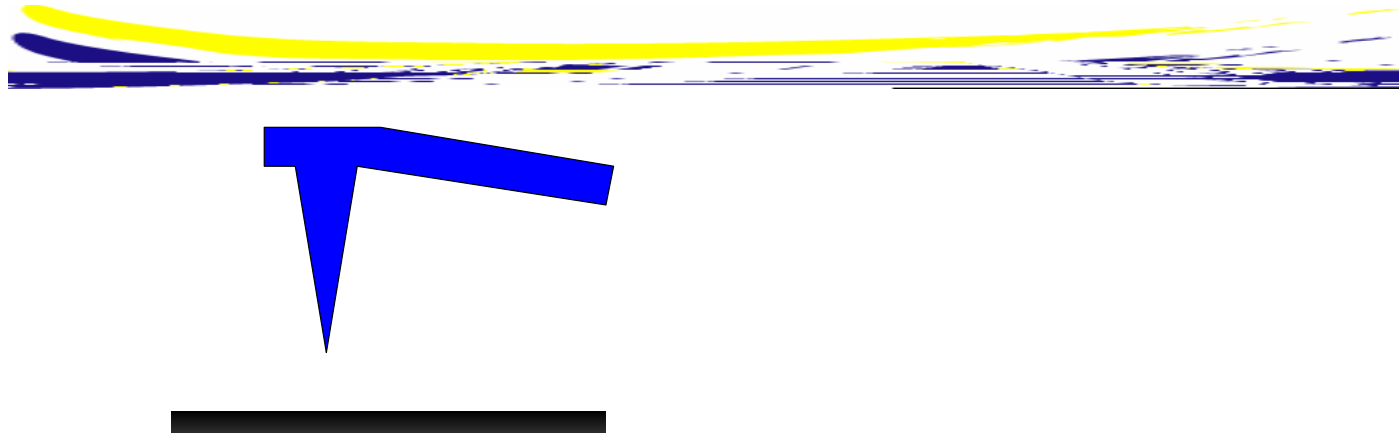
→ Silicon substrate with SiO₂ thermal oxide

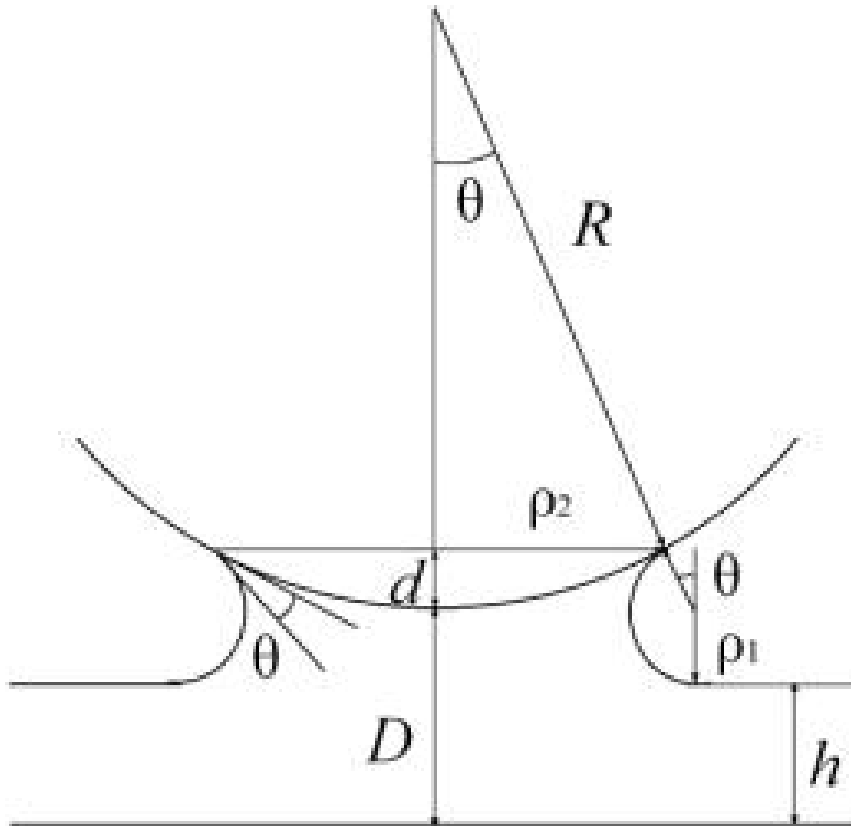


Atomic Force Microscopy (AFM) Study



AFM Force Spectroscopy





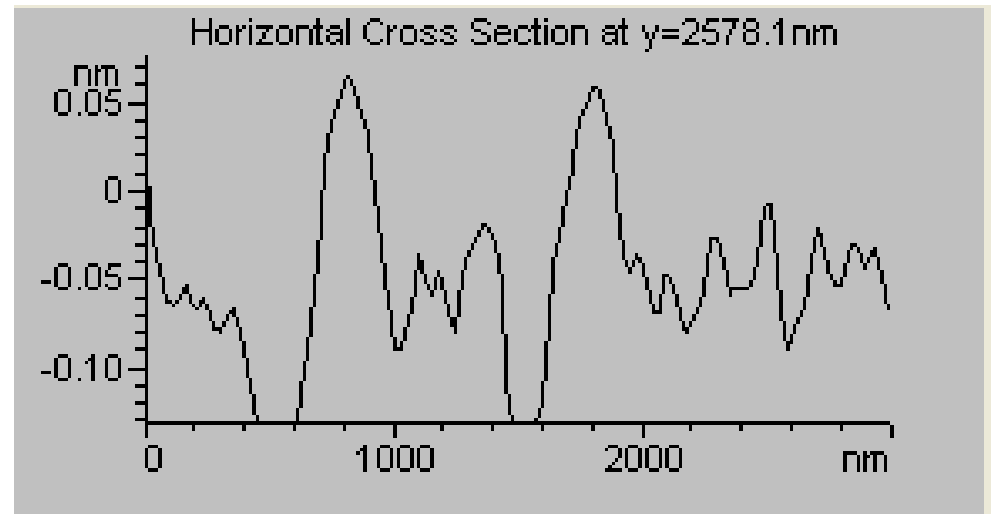
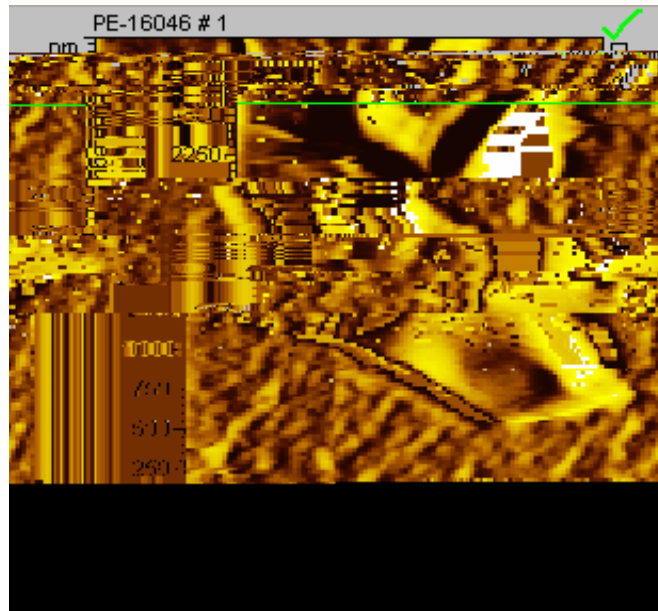
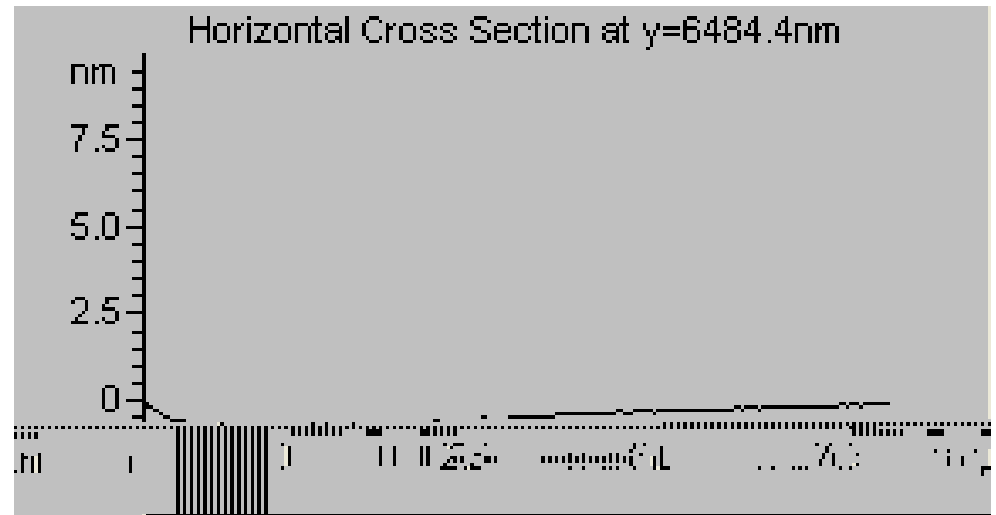
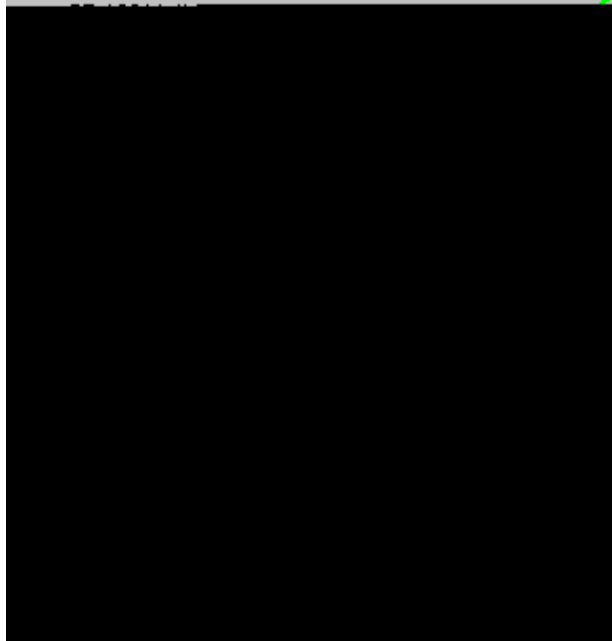
$$\sigma = \frac{F_{\text{max. attraction}}}{4\pi R \cos \theta}$$

Previous SEM and XPS Results on Peel Ply Surfaces

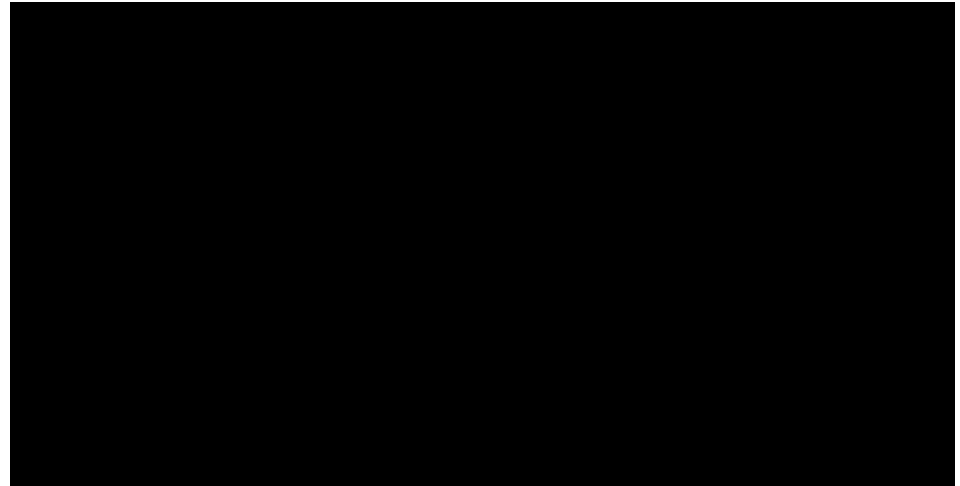
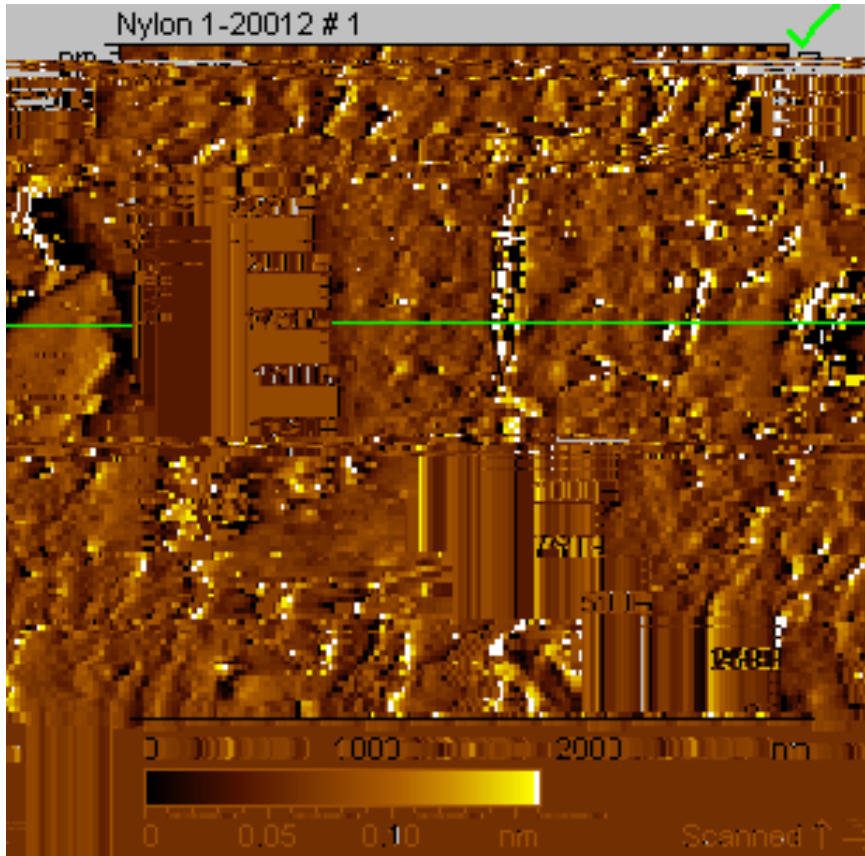


- **Polyester (PF 60001): No transfer, strong bonds**
- **SRB (PF 60001): Siloxane coating transfer, weak bonds**
- **Nylon (PF 52006): Fiber transfer, bond strength depends on adhesive**

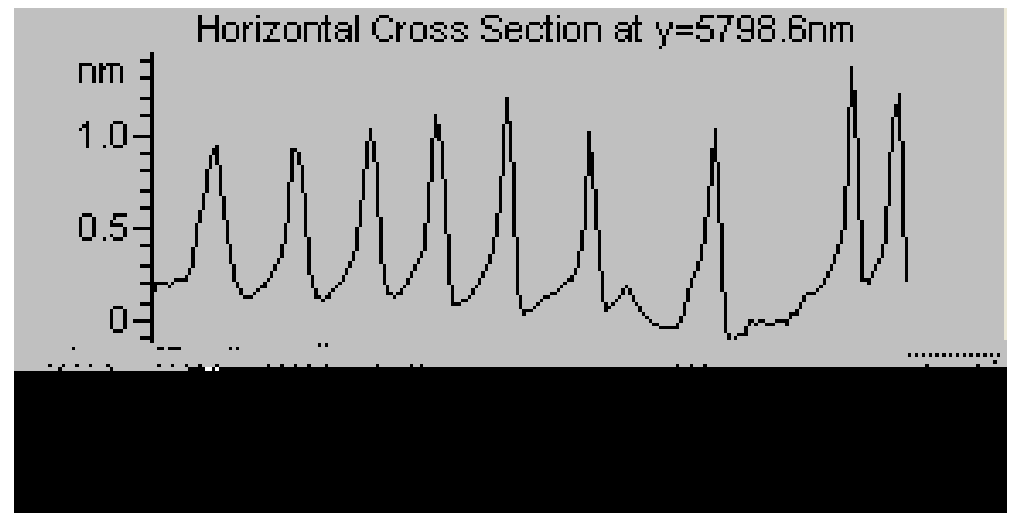
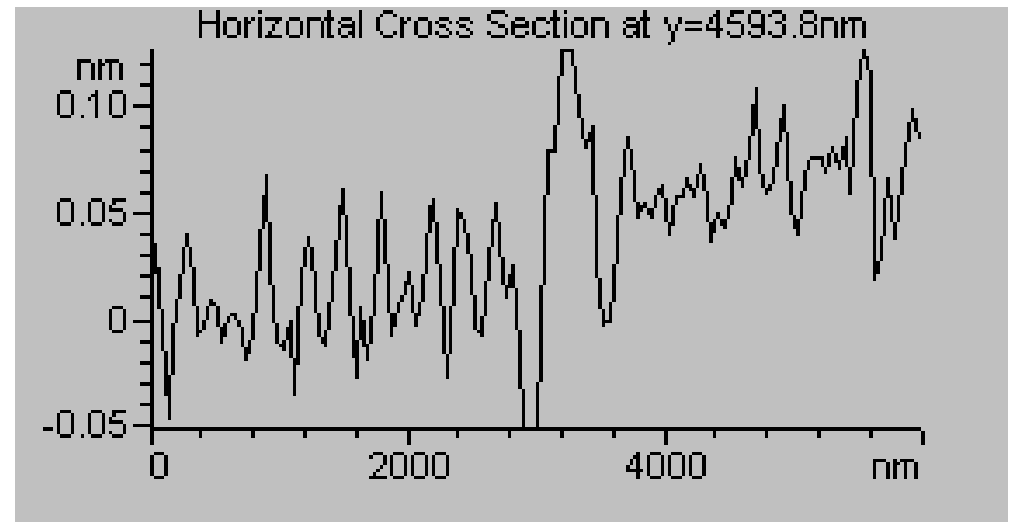
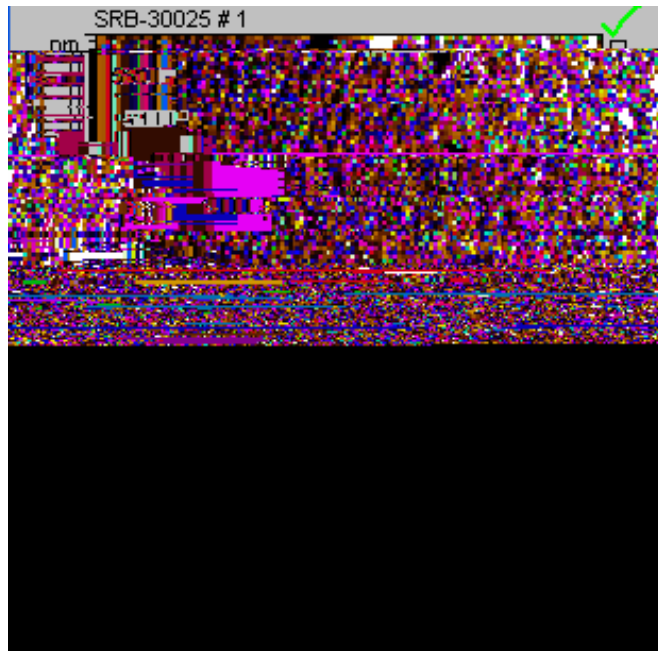
Polyester Peel Ply Surface



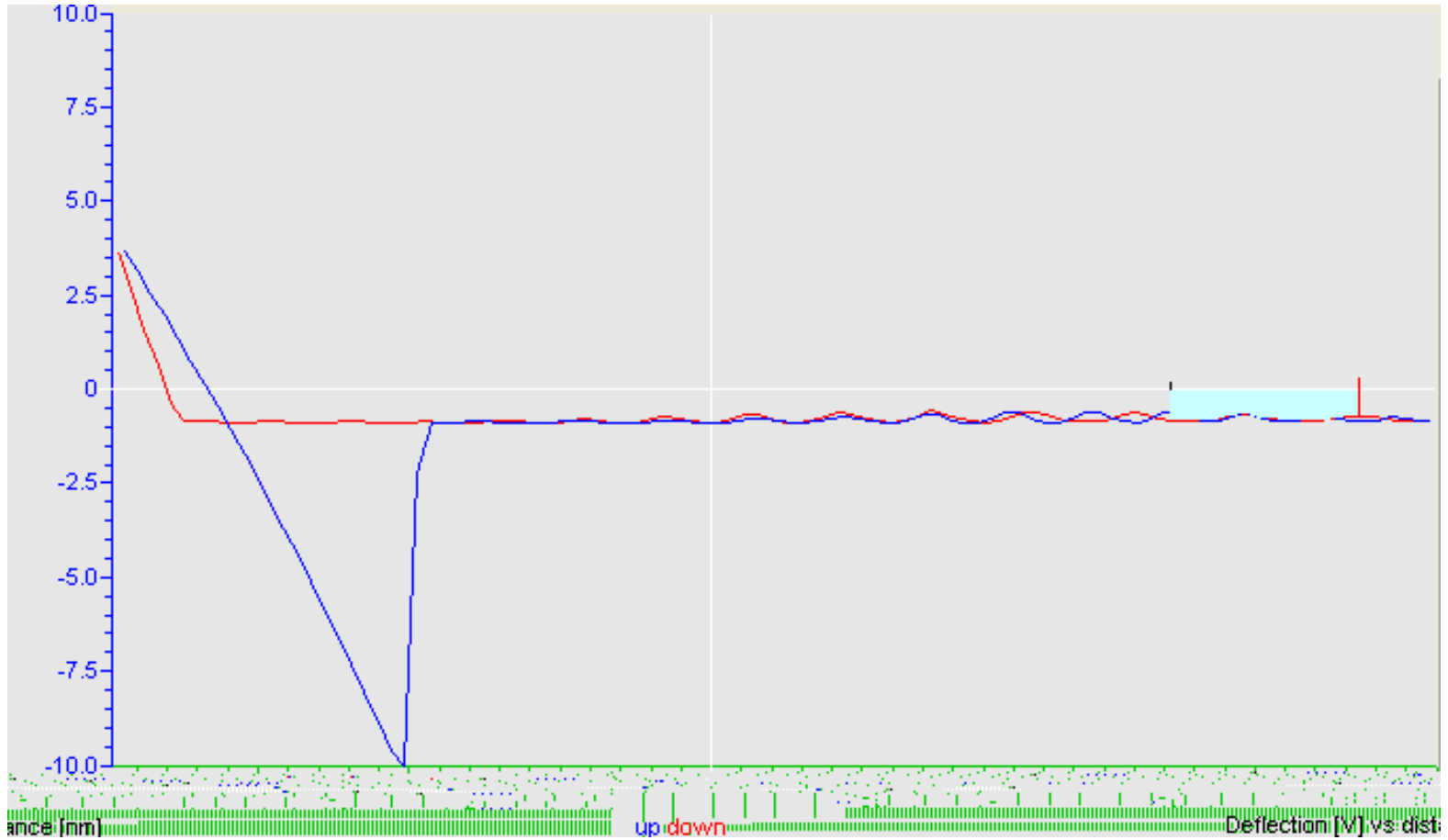
Nylon Peel Ply Surface



SRB Peel Ply Surface



Typical Force vs. Distance For PE Peel Ply Prepared Surface







- AFM can evaluate the conclusions

Benefit to Aviation

- Better understanding of the pre-bond surface preparation methods
- Better understanding of bond strength and durability versus surface preparation
- Novel in-field, online certification and assurance technology for surface preparation
- Reduced costs for surface preparation and adhesive bonding processes

Future needs

- In-field, online analytical detection and monitoring technologies for manufacture, chemical, environmental, and energy industries.